

Electronic Patent Application Fee Transmittal

Application Number:	10791191			
Filing Date:	02-Mar-2004			
Title of Invention:	METHOD OF IMPROVING COPPER INTERCONNECTS OF SEMICONDUCTOR DEVICES FOR BONDING			
First Named Inventor/Applicant Name:	Salman Akram			
Filer:	James R. Duzan/Leta Howard			
Attorney Docket Number:	3854.3US (98-0854.03/US)			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180